

Custom Hybrid, MCM, Module, Box Assembly and Testing Services

Fact Sheet

June 2012

www.aeroflex.com/EMS



INTRODUCTION

Aeroflex Plainview, a supplier of standard products and custom microelectronic solutions offers Space and Military qualified assembly and test services meeting the requirements of MIL-PRF-38534 Class H & K. In addition, Aeroflex Plainview has been accredited by the Department of Defense as a Trusted Source, Category 1A supplier for assembly services.

Our MCM packaging technology enables our customers to realize the optimum Size, Weight and Power (SWaP) of their products by applying flip-chip, chip and wire, Chip-on-Board (COB), Surface Mount Technology (SMT) and Planar Magnetics. In many cases, more than one of these technologies are combined in a single module.

From DC to 40GHz, Aeroflex can provide microelectronic packaging and test solutions for high speed digital, precision analog and RF/Microwave devices used in military, space and critical industrial applications.

AEROFLEX Offers:

- One stop solution for your microelectronic assembly, evaluation, test and screening requirements
- MIL-PRF-38534 compliant (Class H & K), ISO-9001 and AS9100 certified
- Customer furnished tooling - Aeroflex is experienced in integrating customer originated designs into a smooth, seamless high quality process.
- Full turnkey and “design to spec” services for hybrid, SMT assemblies and boxes.
- Vertically integrated die to box facility, Class 1,000, Class 10,000 and Class 100,000 manufacturing space.
- High reliability Chip on Board design and manufacturing services
- RF/Microwave manufacturing services for high volume phased array antennas
- Value-added services such as radiation testing and characterization, classified testing and COTS / commercial upscreening
- Aeroflex HiRel products, such as FPGAs and ASICs, are available for vertical integration
- Off Shore assembly available for large volume: Hi-Rel, telecom and military applications

PRODUCTION CAPABILITIES

Aeroflex Plainview can provide a complete solution for your microelectronic assembly, evaluation, test and screening requirements.

- Assembly
 - Wafer saw and electrical probe
 - Assembly and wirebond
 - State-of-the Art gold ball bonding: 90µ pitch available
 - Large Area – 16" x 13" bondable area
 - 1 mil to 2 mil automatic gold ball bonding
 - Gold and aluminium wedge bonding
 - Heavy Aluminium – 4 mil to 20 mil wire
 - Ribbon Bonding – .25 mil x 3 mil to 2 mil x 10 mil
 - Vacuum brazing – Eutectic die and substrate attach
 - GaAs MMIC gold-tin die attach
 - Epoxy die bonding to 7µ placement accuracy
 - Gap welding – beam lead diodes / wire / ribbon
 - Active laser trim of thick and thin film resistors
 - RF / Microwave Tuning
 - Hi-Rel Chip-On-Board assemblies / SMT (See Figure 4/5)
 - Hermetic or epoxy package sealing
 - Plastic packages / flip chips
 - Transformers / coils
 - Internal preseal visual
 - MIL-STD-883, Method 2010 or 2017, Cond A or B
 - Hermetic packages available
 - LCC, PGA, QFP, DIP, FP, TO cans, ring frame, Multi-Chip Modules (MCM), SOIC, CCGA, LGA
 - Solder dip - MIL-STD-883, Method 2003
- Electrical test
 - Wafer level DC parametrics
 - Memory, logic and analog IC testing
 - Wafer probe and package IC testing
 - RF testing to 40GHz
- Burn-In Services
 - Static/Dynamic burn-in
- Environmental test per MIL-STD-883 Test Methods
 - Hermeticity – Method 1014, Cond A1, A2, C3
 - PIND – Method 2020, Cond A, B
 - X-Ray Radiographic – Method 2012
 - Centrifuge – Method 2001
 - Temp cycle – Method 1010
 - Mechanical shock and variable vibration – Method 2007
 - Thermal vacuum testing

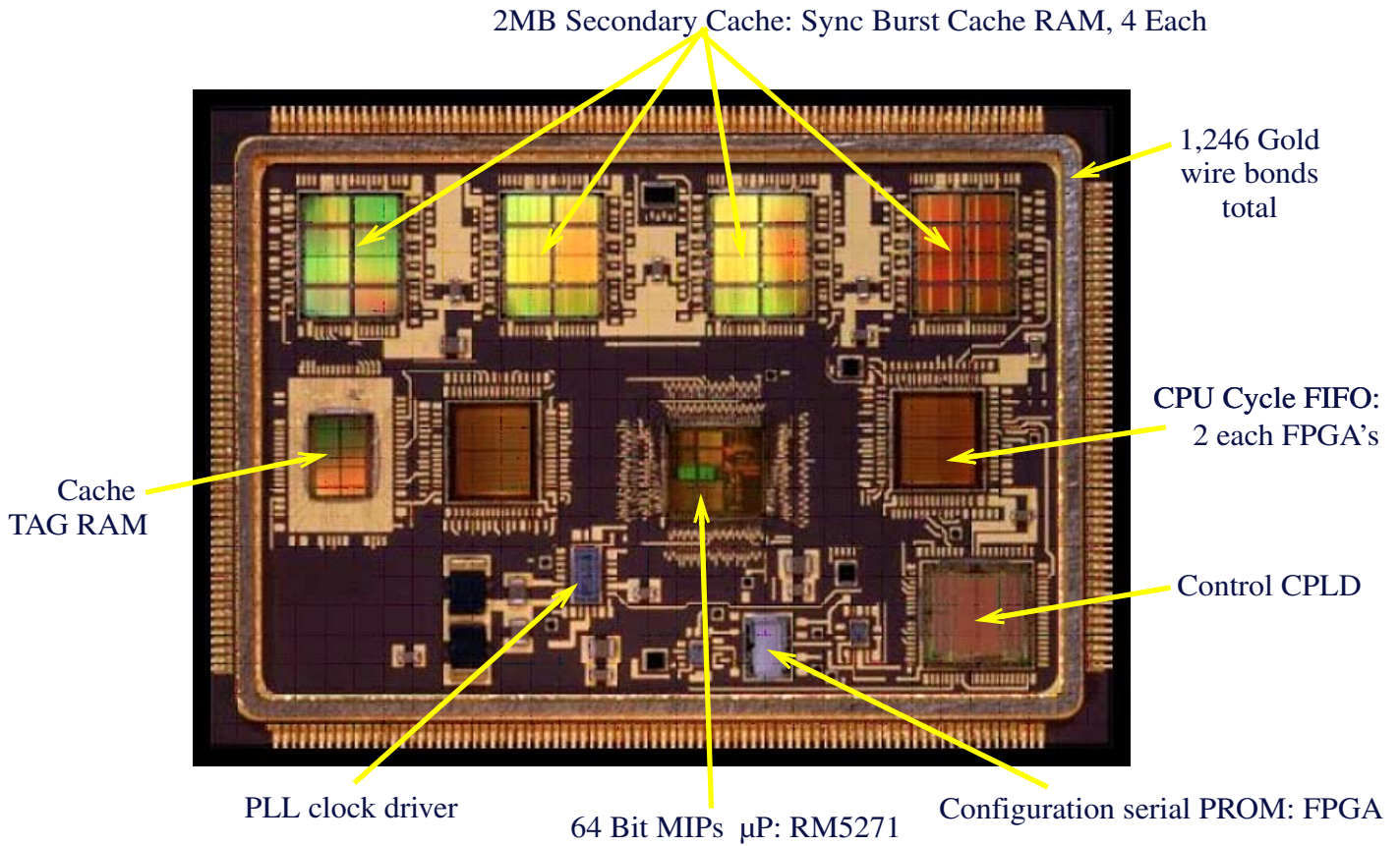


FIGURE 1 – Microprocessor MCM – ACT-5271SC-F10-M21C

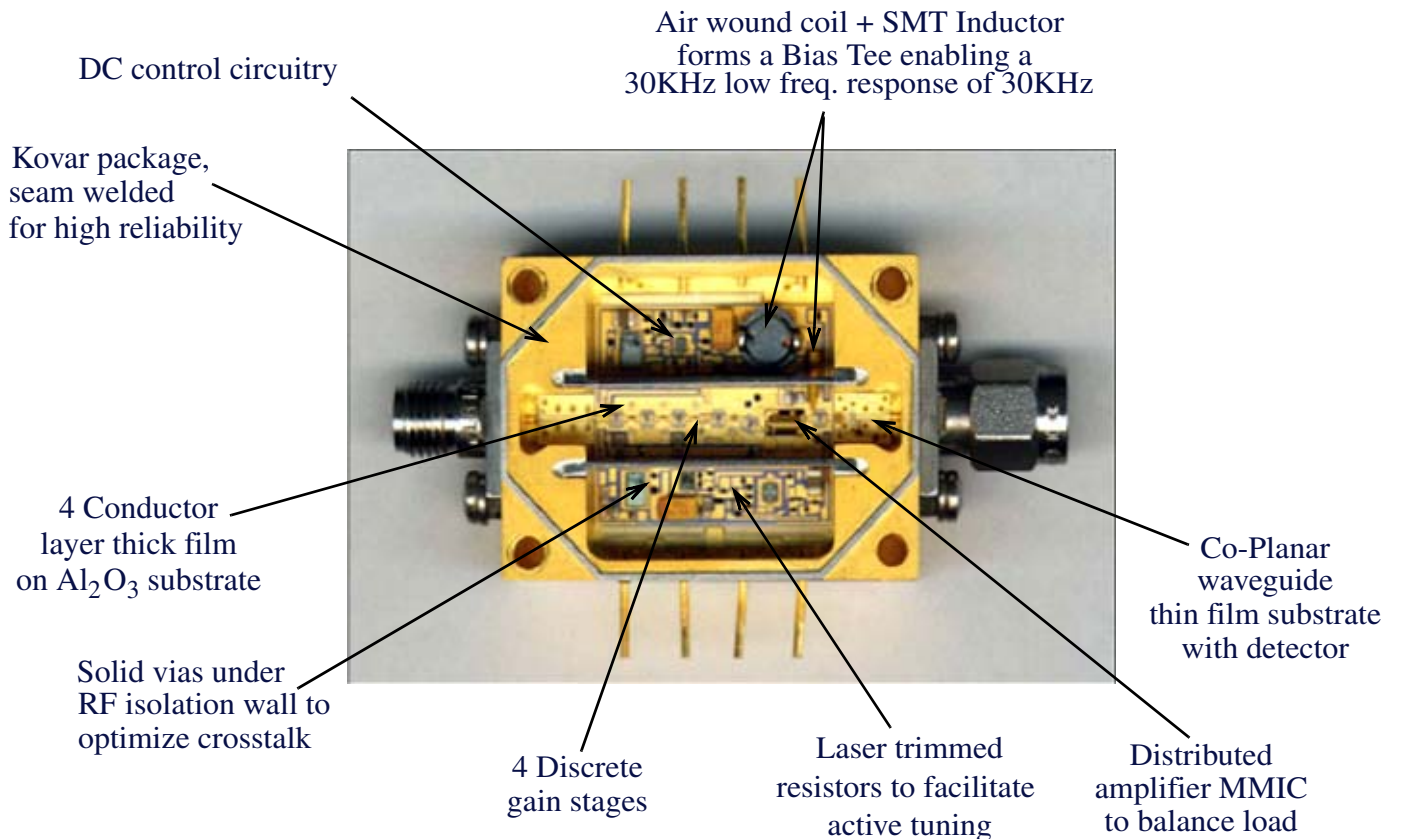


FIGURE 2 – Highly Integrated 10GHz RF Module – AMPF-128MDA



FIGURE 3 – Box Assembly, Li Battery Electronic Unit (BEU)

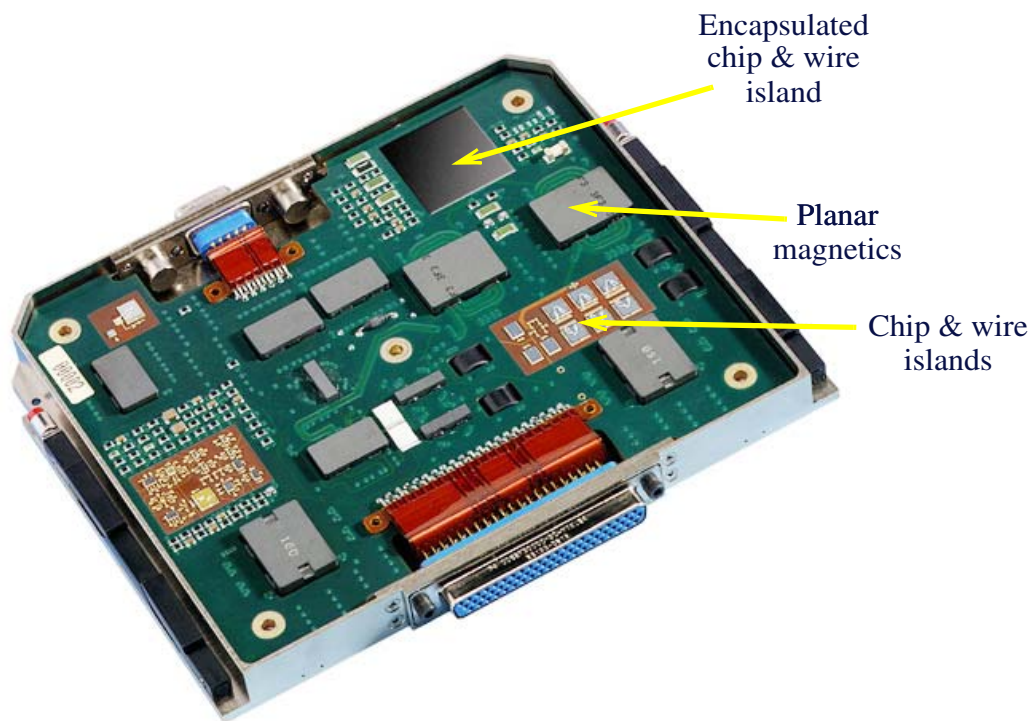
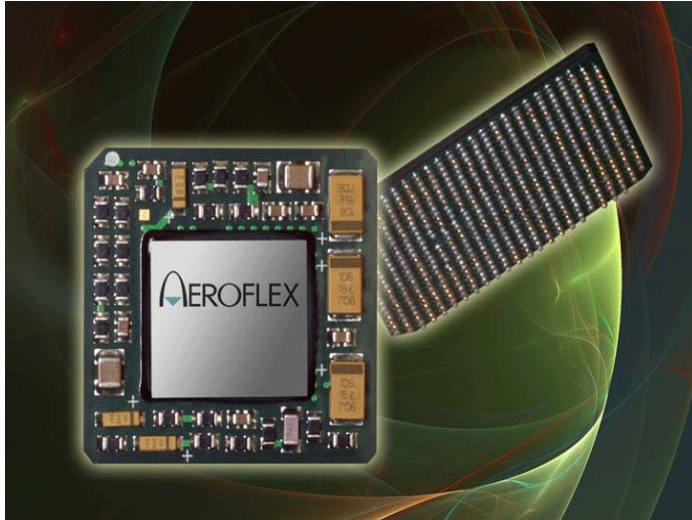


FIGURE 4 – DC-DC Converter, Plug-and-Play Low-Voltage Power Supply, +28V Input. Output: +5V, +3.3V, +2.5V, 70W – ACT8616



- High I/O Count
- Ideal for Mixed Signal Applications
- Hermetic Seal over Die Island
- Suitable to 2 GHz
- Polyimide PWB for High Reliability Applications
- Low Mass allows device to be automatically picked & placed
- Ability to overcome Obsolescence
- MIL-PRF-38534 Qualification

FIGURE 5 – Chip On Board MCM BGA Assembly

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